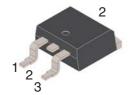
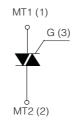
RoHS



HIGH COMMUTATION TRIAC

TO-263AB (D2PAK)





On-State Current

Gate Trigger Current

16 Amp

≤ 50 mA

Off-State Voltage

400 V ÷ 800 V

FEATURES

- Glass/passivated die junctions
- Medium current Triac
- Low thermal resistance
- Ideal for automated placement



- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- Component in accordance to RoHS 2011/65/EU and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C

MECHANICAL DATA

- Case: TO-263AB (D2PAK). Epoxy meets UL 94V-0 flammability rating.
- Polarity: As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

TYPICAL APPLICATIONS

 Used on inductive loads, thanks to their high commutation performances.

Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I _{T(RMS)}	RMS On-state Current (full sine wave)	All Conduction Angle, T _c = 95 °C	16	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz (t = 16.7 ms)	176	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz (t = 20 ms)	160	А
I ² t	Fusing Current	tp = 10 ms, Half Cycle	128	A ² s
I _{GM}	Peak Gate Current	20 μs max. Tj = 125 °C	4	А
P _{G(AV)}	Average Gate Power Dissipation	Tj = 125 °C	1	W
dI/dt	Critical rate of rise of on-state current	$I_G = 2x I_{GT}, t_r \le 100 \text{ns}$	50	A/µs
		f = 120 Hz, T _j = 125 °C		
T _j	Operating Temperature		(-40 +125)	°C
T _{stg}	Storage Temperature		(-40 +150)	°C
T _{sld}	Soldering Temperature	10s max	260	°C

SYMBOL	PARAMETER		Unit		
01111202	. ,	D	М	N	0.1110
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	400	600	800	V

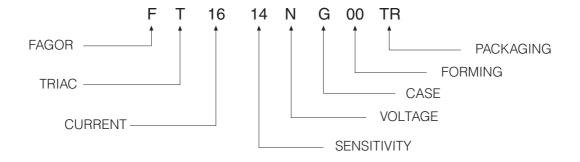


Electrical Characteristics at Tamb = 25 °C

SYMBOL	PARAMETER	CONDITIONS		Quadrant		SENSITIVITY		Unit	
STINIBOL	FANAMETEN			Quaurani		11	14	16	
I _{GT} ⁽¹⁾	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 339$	Ω , $T_j = 25$ °C	Q1÷Q3	MAX	25	35	50	mA
V _{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 339$	Ω , $T_j = 25$ °C	Q1÷Q3	MAX		1.3		V
V_{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \text{ Kg}$	Ω , $T_j = 125 ^{\circ}\text{C}$	Q1÷Q3	MIN	0.2		V	
I _H ⁽²⁾	Holding Current	I _T =100 mA,Gate ope	en, $T_j = 25 ^{\circ}\text{C}$		MAX	25	35	50	mA
IL	Latching Current	$I_{G} = 1.2 I_{GT}, T_{j} = 25 ^{\circ}$	С	Q1, Q3	MAX	40	50	70	mA
				Q2	MAX	50	60	80	
dV/dt (2)	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}, Ga$	ate open		MIN	200	500	1000	V/µs
		T _j = 125 °C							
(dl/dt)c (2)	Critical Rate of Current Rise	$(dv/dt)c = 0.1 V/\mu s$	$T_j = 125 ^{\circ}\text{C}$		MIN	-	-	-	A/ms
		$(dv/dt)c = 10 V/\mu s$	$T_j = 125 ^{\circ}\text{C}$		MIN	-	-	-	
		without snubber	$T_j = 125 ^{\circ}\text{C}$		MIN	6	8.5	14	
V _{TM} ⁽²⁾	On-state Voltage	$I_T = 22.5 \text{ Amp, tp} = 380 \ \mu\text{s,} T_j = 25 \ ^{\circ}\text{C}$			MAX	1.6			V
V _{t (o)} (2)	Threshold Voltage	T _j = 125 °C			MAX		0.77		V
r _d ⁽²⁾	Dynamic resistance	T _j = 125 °C			MAX	70		mΩ	
I _{DRM} /I _{RRM}	Off-State Leakage Current	$V_D = V_{DRM}$	T _j = 125 °C		MAX		2		mA
		$V_R = V_{RRM}$,	$T_j = 25 ^{\circ}C$		MAX		5		μΑ
R _{th(j-c)}	Thermal Resistance Junction-Case	for AC 360° conduction angle					1.1		°C/W
R _{th(j-a)}	Thermal Resistance	$S^{(3)} = 1 \text{ cm}^2$					45		°C/W
	Junction-Ambient								

⁽¹⁾ Minimum I_{GT} is guaranted at 5% of I_{GT} max.

Part Number Information



⁽²⁾ For either polarity of electrode MT2 voltage with reference to electrode MT1.

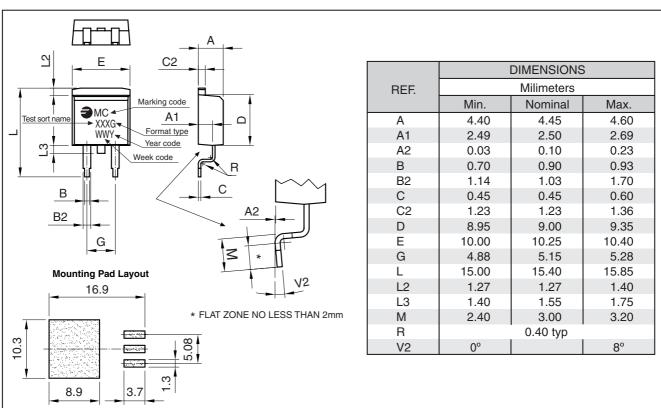
⁽³⁾ S: Cooper surface under tab.



Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FT1614MG 00TR	TR	13" diameter tape and reel	800	1.50

Package Outline Dimensions: (mm) TO-263AB (D2PAK)





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle)

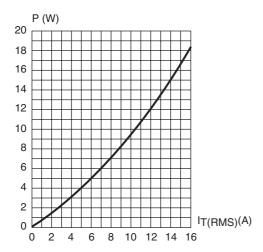


Fig. 3: Relative variation of thermal impedance versus pulse duration.

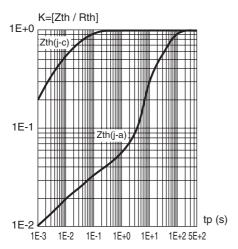


Fig. 5: Surge peak on-state current versus number of cycles

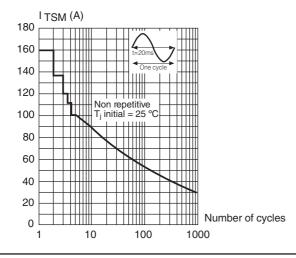


Fig. 2: RMS on-state current versus case temperature (full cycle).

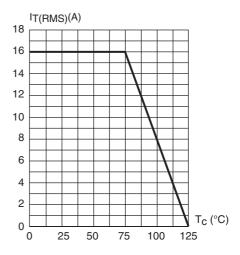


Fig. 4: On-state characteristics (maximum values)

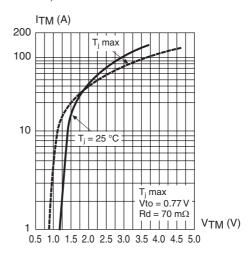
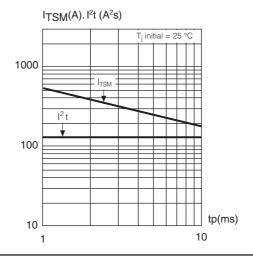


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I²t.





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

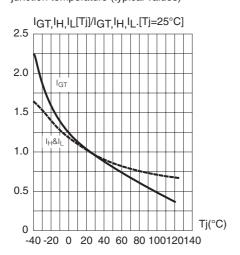
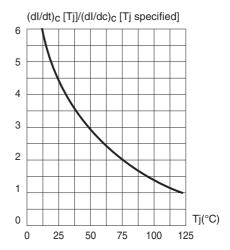


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature





Revision History

Date	Revision	Description of Changes		
12-Oct-2004	0	Original Data Sheet		
10-Oct-2013	1	200V and 700V eliminated, Add Sensitivity 11		

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All product, product specifications and data are subject to change without notice to improve reliability, function or design or otherwise.

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